

Features

- Surface mount packaging for automated assembly
- Small footprint size (1210) and low profile for space-constrained mobile applications
- Ultra-low resistance, quick response
- RoHS compliant*



Additional Information

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PRODUCT TECHNICAL INVENTORY SAMPLES CONTACT SELECTOR LIBRARY

MF-USML/X Series - Low Ohmic PTC Resettable Fuses

Electrical Characteristics

Madal	V _{max}	I _{max}	lhold	Itrip	Resis	stance	Max. Tin	ne To Trip	Tripped Power Dissipation	Agency R	ecognition
Model			at 2	3 °C	at 23 °0	at 23 °C Ohms		at 23 °C		cUL	ΤÜV
	Volts	Amps	An	nps	R _{min}	R _{1max}	Amps	Seconds	Тур.	E174545	R50391579
MF-USML175/6	6	50	1.75	3.5	0.006	0.05	8	0.8	1.0	✓	1
MF-USML175/12	12	50	1.75	3.5	0.006	0.05	8	0.8	1.0	✓	1
MF-USML200/6	6	50	2.0	4.0	0.005	0.04	8	5	1.0	✓	1
MF-USML200/12	12	50	2.0	4.0	0.005	0.04	8	5	1.0	✓	1
MF-USML260/6	6	50	2.6	5.2	0.004	0.03	8	5	1.0	✓	1
MF-USML260/12	12	50	2.6	5.2	0.004	0.03	8	5	1.0	✓	1
MF-USML300/6	6	50	3.0	6.0	0.003	0.024	15	5	1.0	✓	1
MF-USML300/12	12	50	3.0	6.0	0.003	0.024	15	5	1.0	✓	1
MF-USML350/6	6	50	3.5	7.0	0.002	0.022	17	5	1.0	✓	1
MF-USML350/12	12	50	3.5	7.0	0.002	0.022	17	5	1.0	✓	1
MF-USML380/6	6	50	3.8	7.6	0.002	0.02	19	5	1.0	✓	1
MF-USML380/12	12	50	3.8	7.6	0.002	0.02	19	5	1.0	✓	1
MF-USML400/6	6	50	4.0	8.0	0.002	0.018	20	5	1.0	✓	1
MF-USML400/12	12	50	4.0	8.0	0.002	0.018	20	5	1.0	✓	1
MF-USML450/6	6	50	4.5	9.0	0.002	0.014	22.5	2	1.0	✓	1
MF-USML450/12	12	50	4.5	9.0	0.002	0.014	22.5	2	1.0	✓	1
MF-USML500/6	6	50	5.0	10	0.001	0.012	25	2	1.2	✓	1
MF-USML500/12	12	50	5.0	10	0.001	0.012	25	2	1.2	1	1
MF-USML550/6	6	50	5.5	11	0.001	0.01	27.5	2	1.2	✓	1
MF-USML550/12	12	50	5.5	11	0.001	0.01	27.5	2	1.2	✓	1
MF-USML600/6	6	50	6.0	12	0.001	0.01	30	2	1.2	✓	1
MF-USML650/6	6	50	6.5	13	0.001	0.009	32.5	2	1.2	✓	✓
MF-USML700/6	6	50	7.0	14	0.001	0.008	35	2	1.2	✓	1

Environmental Characteristics

Item		Condition	Criteria		
Operating Temperatu	re	-40 °C to +85 °C			
Otomore Condition	Before Opening	+40 °C max. / 70 % RH max.			
Storage Condition	After Opening	+40 °C max. / 10 % RH max.			
Floor Condition After Opening		Consumption within 4 weeks at floor condition +30 °C max. / 60 % RH max.			
Passive Aging		+85 °C, 1000 hours	±10 % typical resistance change		
Humidity Aging		+85 °C, 85 % R.H. 100 hours	±15 % typical resistance change		
Thermal Shock		-40 °C to +85 °C, 20 times	±30 % typical resistance change		
Solvent Resistance		MIL-STD-202, Method 215	No change (marking still legible)		
Vibration		MIL-STD-883C, Method 2007.1 Condition A	No change (R _{min} < R < R _{1max})		
Moisture Sensitivity L	evel (MSL)	See Note			
ESD Classification		Class 6 (per AEC-Q200-2, HBM)			



^{*} RoHS Directive 2015/863, Mar 31, 2015 and Annex.

 $[\]ensuremath{^{**}}$ Bourns considers a product to be "halogen free" if (a) the Bromine (Br) content is 900 ppm or less; (b) the Chlorine (CI) content is 900 ppm or less; and (c) the total Bromine (Br) and Chlorine (Cl) content is 1500 ppm or less.

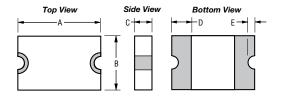
Test Procedures and Requirements

Item	Test Condition	Accept/Reject Criteria		
Visual/Mechanical	Verify dimensions and materials	Per MF physical description		
Resistance	In still air @ 23 °C	$R_{min} \le R \le R_{max}$		
Time to Trip	At specified current, V _{max} , 23 °C, still air	T ≤ max. time to trip (seconds)		
Hold Current	30 min. at I _{hold} , still air	No trip		
Trip Cycle Life	V _{max} , I _{max} , 100 cycles	No arcing or burning		
Trip Endurance	V _{max} , 48 hours	No arcing or burning		
Solderability	245 °C ±5 °C, 5 seconds	95 % min. coverage		

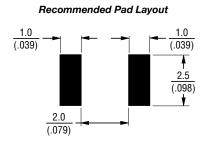
Product Dimensions

Model	A		В		С		D	E	
Model	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.	Max.
MF-USML175/6									
MF-USML175/12									
MF-USML200/6	3.0	3.43 (.135)	2.35	2.8 (.110)	<u>0.4</u> (.016)	0.70			
MF-USML200/12	(.118)	(.135)	(.093)	(.110)	(.016)	<u>0.70</u> (.028)			
MF-USML260/6									
MF-USML260/12									
MF-USML300/6									
MF-USML300/12									
MF-USML350/6									
MF-USML350/12									
MF-USML380/6	1						0.05	0.05	0.45
MF-USML380/12]						0.25 (.010)	$\frac{0.05}{(.002)}$	0.45 (.018)
MF-USML400/6	3.0	3.43 (.135)	2.35	<u>2.8</u> (.110)	0.6	1.2 (.047)	(.010)	(.002)	(.016)
MF-USML400/12	3.0 (.118)	(.135)	(.093)	(.110)	(.024)	(.047)			
MF-USML450/6									
MF-USML450/12]								
MF-USML500/6	1								
MF-USML500/12]								
MF-USML550/6]								
MF-USML550/12									
MF-USML600/6	2.0	2.42	0.05	0.0	0.6	0.05			
MF-USML650/6	3.0 (.118)	3.43 (.135)	2.35 (.093)	2.8 (.110)	$\frac{0.6}{(.024)}$	0.95 (.037)			
MF-USML700/6	(.110)	(.133)	(.093)	(.110)	(.024)	(.037)			

MM DIMENSIONS: (INCHES)



Terminal material: **ENIG-plated terminals**



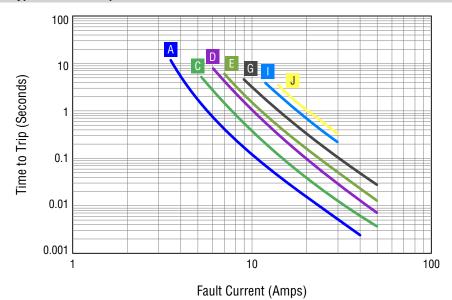
Packaging Quantity

MF-USML175/6 \sim MF-USML260/6 = 5000 pcs. per reel MF-USML175/12 ~ MF-USML260/12 = 5000 pcs. per reel MF-USML300/6 \sim MF-USML700/6 = 3500 pcs. per reel MF-USML300/12 ~ MF-USML550/12 = 3500 pcs. per reel

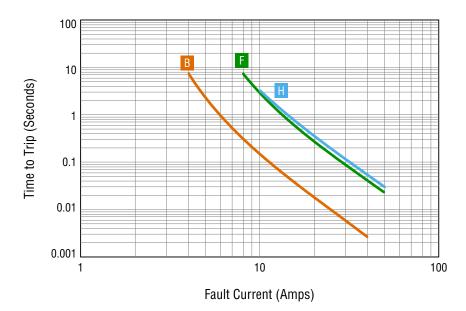
Thermal Derating Table - Ihold (Amps)

Madal	Ambient Operating Temperature									
Model	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C	
MF-USML175/6	2.57	2.33	2.07	1.75	1.49	1.34	1.24	1.0	0.88	
MF-USML175/12	2.57	2.33	2.07	1.75	1.49	1.34	1.24	1.0	0.88	
MF-USML200/6	2.94	2.65	2.35	2.0	1.7	1.53	1.42	1.14	1.0	
MF-USML200/12	2.94	2.65	2.35	2.0	1.7	1.53	1.42	1.14	1.0	
MF-USML260/6	3.82	3.46	3.07	2.6	2.21	1.95	1.85	1.48	1.3	
MF-USML260/12	3.82	3.46	3.07	2.6	2.21	1.95	1.85	1.48	1.3	
MF-USML300/6	4.41	3.99	3.54	3.0	2.55	2.3	2.13	1.71	1.5	
MF-USML300/12	4.41	3.99	3.54	3.0	2.55	2.3	2.13	1.71	1.5	
MF-USML350/6	5.1	4.65	4.13	3.5	2.98	2.65	2.5	2.0	1.75	
MF-USML350/12	5.1	4.65	4.13	3.5	2.98	2.65	2.5	2.0	1.75	
MF-USML380/6	5.59	5.05	4.48	3.8	3.23	2.95	2.7	2.17	1.9	
MF-USML380/12	5.59	5.05	4.48	3.8	3.23	2.95	2.7	2.17	1.9	
MF-USML400/6	5.8	5.25	4.7	4.0	3.4	3.1	2.8	2.28	2.0	
MF-USML400/12	5.8	5.25	4.7	4.0	3.4	3.1	2.8	2.28	2.0	
MF-USML450/6	6.3	5.65	4.95	4.5	3.83	3.4	2.95	2.5	2.05	
MF-USML450/12	6.3	5.65	4.95	4.5	3.83	3.4	2.95	2.5	2.05	
MF-USML500/6	7.0	6.25	5.5	5.0	4.25	3.75	3.25	2.75	2.25	
MF-USML500/12	7.0	6.25	5.5	5.0	4.25	3.75	3.25	2.75	2.25	
MF-USML550/6	7.7	6.9	6.05	5.5	4.68	4.15	3.6	3.05	2.4	
MF-USML550/12	7.7	6.9	6.05	5.5	4.68	4.15	3.6	3.05	2.4	
MF-USML600/6	8.4	7.5	6.6	6.0	5.1	4.5	3.9	3.3	2.65	
MF-USML650/6	9.1	8.15	7.15	6.5	5.5	4.9	4.25	3.6	2.85	
MF-USML700/6	9.8	8.75	7.7	7.0	5.95	5.25	4.55	3.85	3.05	

Typical Time to Trip at 23 °C



- MF-USML175/6 & MF-USML175/12
- MF-USML260/6 & MF-USML260/12
- MF-USML300/6 & MF-USML300/12
- MF-USML350/6 & MF-USML350/12
- MF-USML450/6 & MF-USML450/12 MF-USML600/6 & MF-USML650/6
- J MF-USML700/6



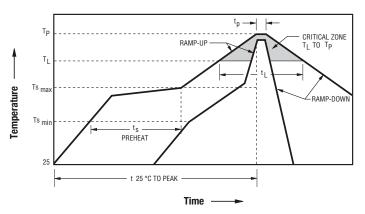
- B MF-USML200/6 & MF-USML200/12
- F MF-USML380/6, MF-USML380/12, MF-USML400/6 & MF-USML400/12
- MF-USML500/6, MF-USML500/12, MF-USML550/6 & MF-USML550/12

The Time to Trip curves represent typical performance of a device in a simulated application environment.

Actual performance in specific customer applications may differ from these values due to the influence of other variables

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Solder Reflow Recommendations



Notes:

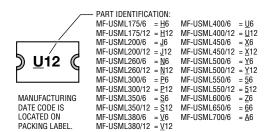
- MF-USML/X models are intended for reflow soldering (including, but not limited to heating plate, hot air, IR, nitrogen, and vapor phase).
- Wave soldering is permissible only if the device is on the top of the PCB, opposite the heat source.
- · Hand soldering is not recommended for these devices.
- All temperatures refer to the topside of the device, measured on the device body surface.
- If reflow temperatures exceed the recommended profile, devices may not meet the published specifications.
- · Compatible with Pb and Pb-free solder reflow profiles.
- · Excess solder may cause a short circuit.
- Please refer to the Multifuse® Polymer PTC Resettable Fuse Soldering Recommendations document for more detai

Profile Feature	Pb-Free Assembly				
Average Ramp-Up Rate (Ts _{max} to T _p)	3 °C / second max.				
PREHEAT:					
Temperature Min. (Ts _{min})	150 °C				
Temperature Max. (Ts _{max})	200 °C				
Time (Ts _{min} to Ts _{max}) (ts)	60~180 seconds				
TIME MAINTAINED ABOVE:					
Temperature (T _L)	217 °C				
Time (t _L)	60~150 seconds				
Peak Temperature (T _p)	260 °C				
Time within 5 °C of Actual Peak Temperature (t _p)	20~40 seconds				
Ramp-Down Rate	6 °C / second max.				
Time 25 °C to Peak Temperature	8 minutes max.				

MF - USML 400 / 12 - 2 Multifuse® Product Designator Series USML = 1210 Low Ohmic Surface Mount Component Hold Current, Ihold 175 - 700 (1.75 Amps - 7.0 Amps) Maximum Voltage, Vmax 12 = 12 Volts 6 = 6 Volts Packaging -2 = Tape and Reel Packaged per EIA-481

Typical Part Marking

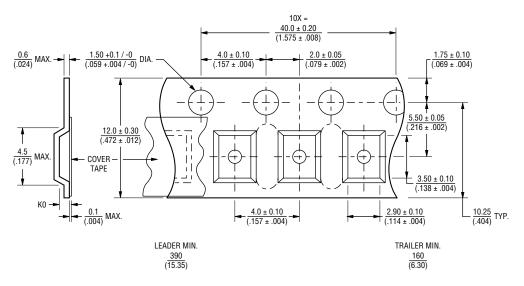
Represents total content. Layout may vary.

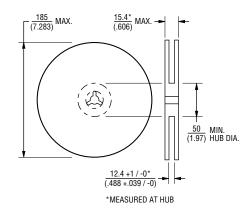


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Packaging Specifications

MF-USML/X Series per EIA-481





DIMENSIONS:

MM (INCHES)

BOURNS®

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MF-USML/X SERIES, REV. C, 10/21

Bourns® Multifuse® PPTC Resettable Fuses

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Application Notice

- Users are responsible for independent and adequate evaluation of Bourns® Multifuse® Polymer PTC devices in the user's
 application, including the PPTC device characteristics stated in the applicable data sheet.
- Polymer PTC devices must not be allowed to operate beyond their stated maximum ratings. Operation in excess of such
 maximum ratings could result in damage to the PTC device and possibly lead to electrical arcing and/or fire. Circuits with
 inductance may generate a voltage above the rated voltage of the polymer PTC device and should be thoroughly evaluated
 within the user's application during the PTC selection and qualification process.
- Polymer PTC devices are intended to protect against adverse effects of temporary overcurrent or overtemperature
 conditions up to rated limits and are not intended to serve as protective devices where overcurrent or overvoltage conditions
 are expected to be repetitive or prolonged.
- In normal operation, polymer PTC devices experience thermal expansion under fault conditions. Thus, a polymer PTC
 device must be protected against mechanical stress, and must be given adequate clearance within the user's application to
 accommodate such thermal expansion. Rigid potting materials or fixed housings or coverings that do not provide adequate
 clearance should be thoroughly examined and tested by the user, as they may result in the malfunction of polymer PTC
 devices if the thermal expansion is inhibited.
- Exposure to lubricants, silicon-based oils, solvents, gels, electrolytes, acids, and other related or similar materials may adversely affect the performance of polymer PTC devices.
- Aggressive solvents may adversely affect the performance of polymer PTC devices. Conformal coating, encapsulating, potting, molding, and sealing materials may contain aggressive solvents including but not limited to xylene and toluene, which are known to cause adverse effects on the performance of polymer PTCs. Such aggressive solvents must be thoroughly cured or baked to ensure their complete removal from polymer PTCs to minimize the possible adverse effect on the device.
- Recommended storage conditions should be followed at all times. Such conditions can be found on the applicable data sheet and on the Multifuse® Polymer PTC Moisture/Reflow Sensitivity Classification (MSL) note: https://www.bourns.com/docs/RoHS-MSL/msl mf.pdf